

# Printoganth<sup>®</sup> MV TP2

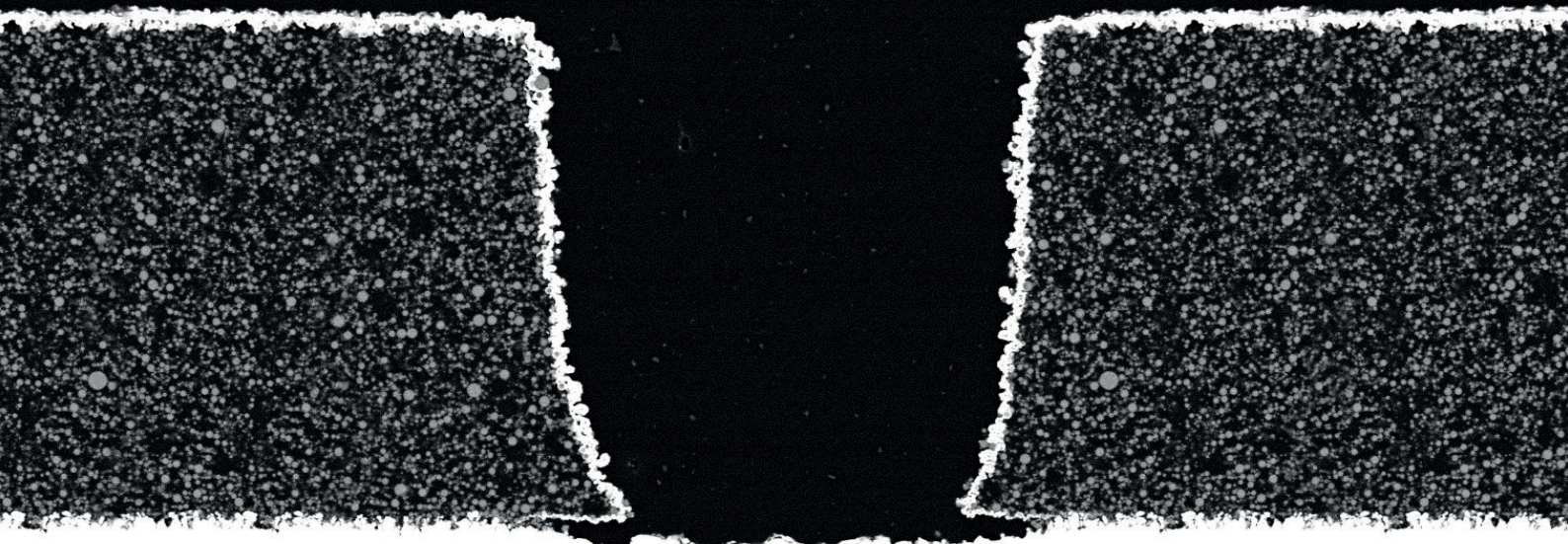
Next generation SAP electroless Copper



Electronics

Desmear and metallization

atotech.com



## Excellent throwing power with predictable deposition rate

Throwing power

> 80%

### Development for SAP fine line product manufacturing

In order to manufacture  $L/S \leq 8/8 \mu\text{m}$  with the SAP process, it is necessary to minimize the differential etching amount. This is typically done through reducing the electroless Cu thickness.

Printoganth<sup>®</sup> MV TP2 has been specifically developed to achieve a low Copper thickness with very good coverage and blister-free deposits on low roughness build-up layer materials. For existing SAP production, matching your current deposition thickness is easily achieved through simply adjusting panel dwell time.

Utilizing a new stabilizer-moderator system, Printoganth<sup>®</sup> MV TP2 creates an enhanced micro rough electroless Cu layer for improved dry film adhesion. With a low requirement for dummy plating, it also offers best process performance with reduced operating costs.

# Cost savings through less dummy plating after make-up or long downtimes

## Features and benefits

- Excellent throwing power into BMVs
- Reduced process costs due to lower dummy plating requirement
- Low bath initiation: 0.2 dm<sup>2</sup> c.b./L for 10min
- Bath loading factor: ≥ 0.1 dm<sup>2</sup> c.b./L
- Predictable and tunable deposition rate
- High volume production: 0.5 μm in 20 min
- Low deposition enables fine line & high frequency production: 0.25 μm in 10 min
- Enhanced surface roughness for improved dry film adhesion
- Ideal for mixed production such as SAP with amSAP
- Stabilizer analysis available

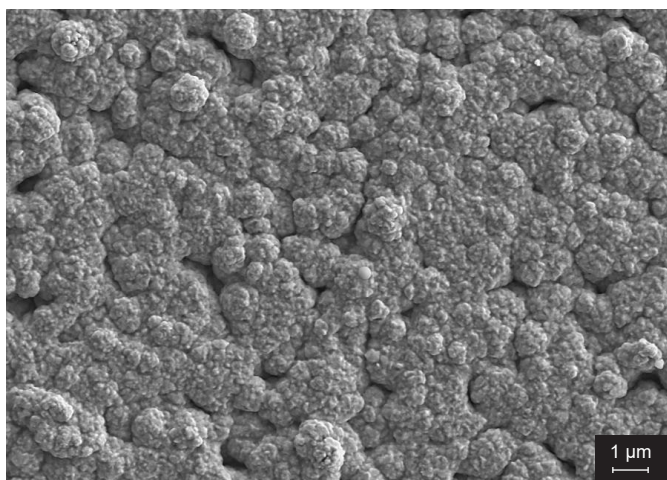


Figure 1: Enhanced micro roughness for dry film adhesion  
ABF GX-92R, Dwell 10 min

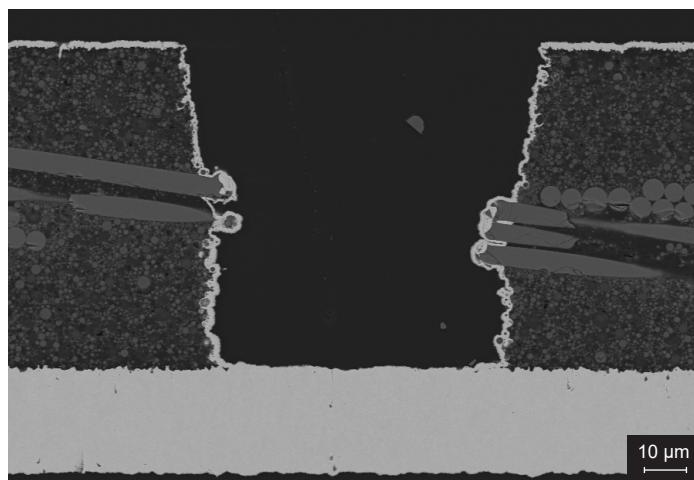


Figure 2: Excellent throwing power  
BT with Cu clad, BMV 90/80 um, Dwell 20 min

